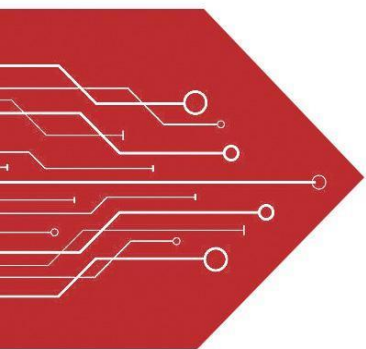


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

Other Data

Body
End termination
Packaging
Complies with Standard

ZnO
Ag/Ni/Sn
Tape
IEC61000-4-2、IEC61000-4-5

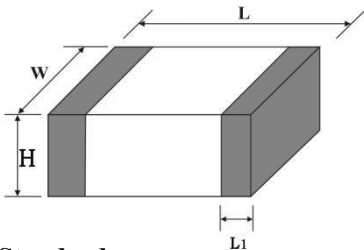
Notes:

- *1 AC voltage at 50~60Hz
- *2 Varistor voltage
- *3 Capacitance
- *4 Maximum clamping voltage
- *5 Rated peak single pulse transient current

Measured at 1mA DC
Measured at f=1kHz, Vrms=0.5V
Measured at 1A by 8/20μs Pulse
Measured by 8/20μs Pulse

Unit: mm

PKG	Length (L)	Width (W)	High (H) Max	Termination (L1)
0603	1.60±0.15	0.80±0.15	0.95	0.35±0.15



Standards

MS 0603 ESDA XX
① ② ③ ④

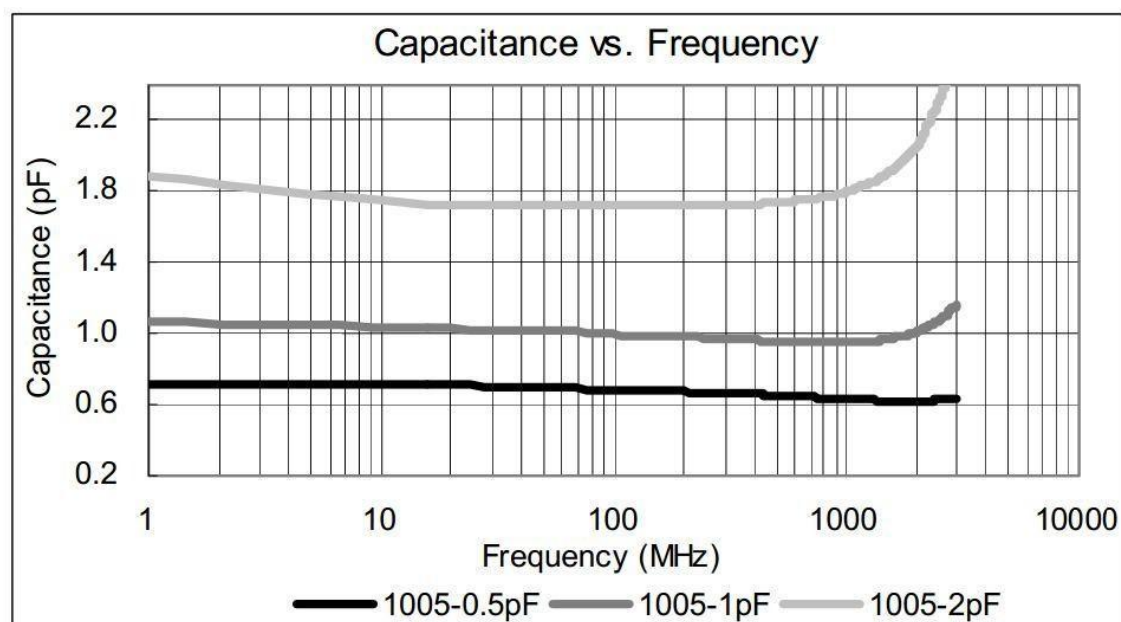
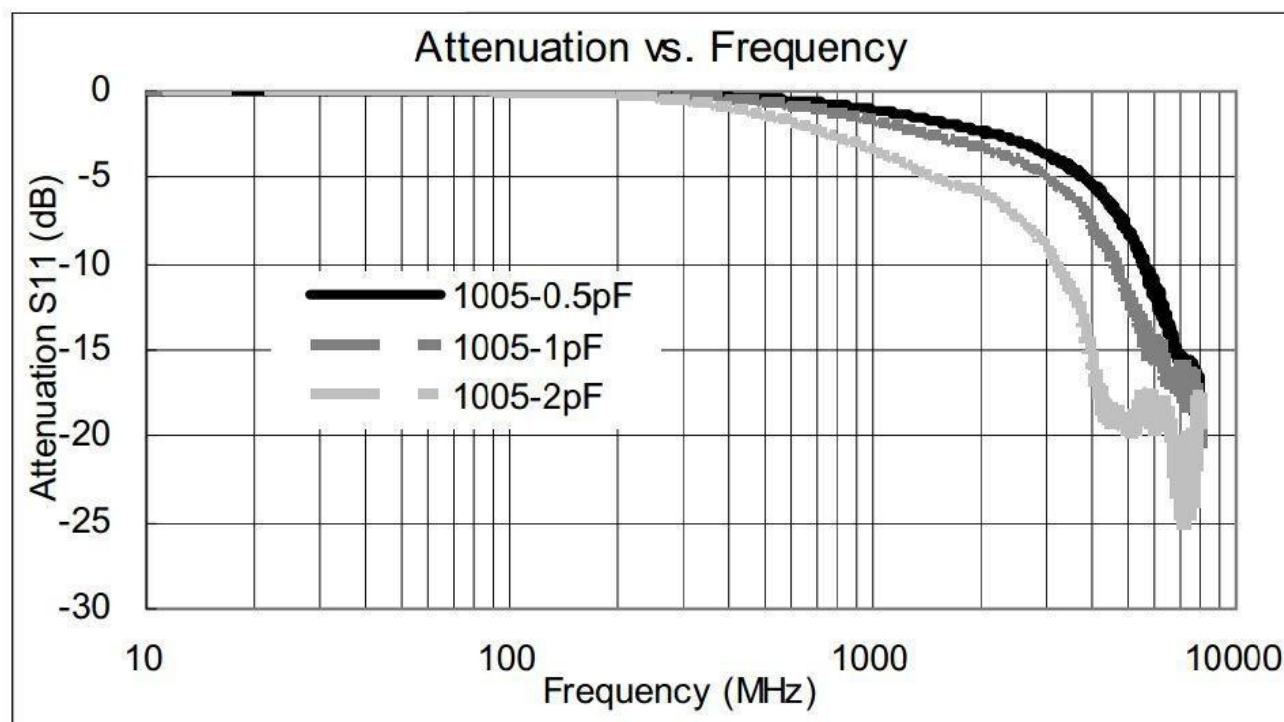
- ①production series: msksemi
- ②size: 0603
- ③type: ESD高分子保护器件
- ④V_{DC}: 5V 9V 12V 14V 18V 24V

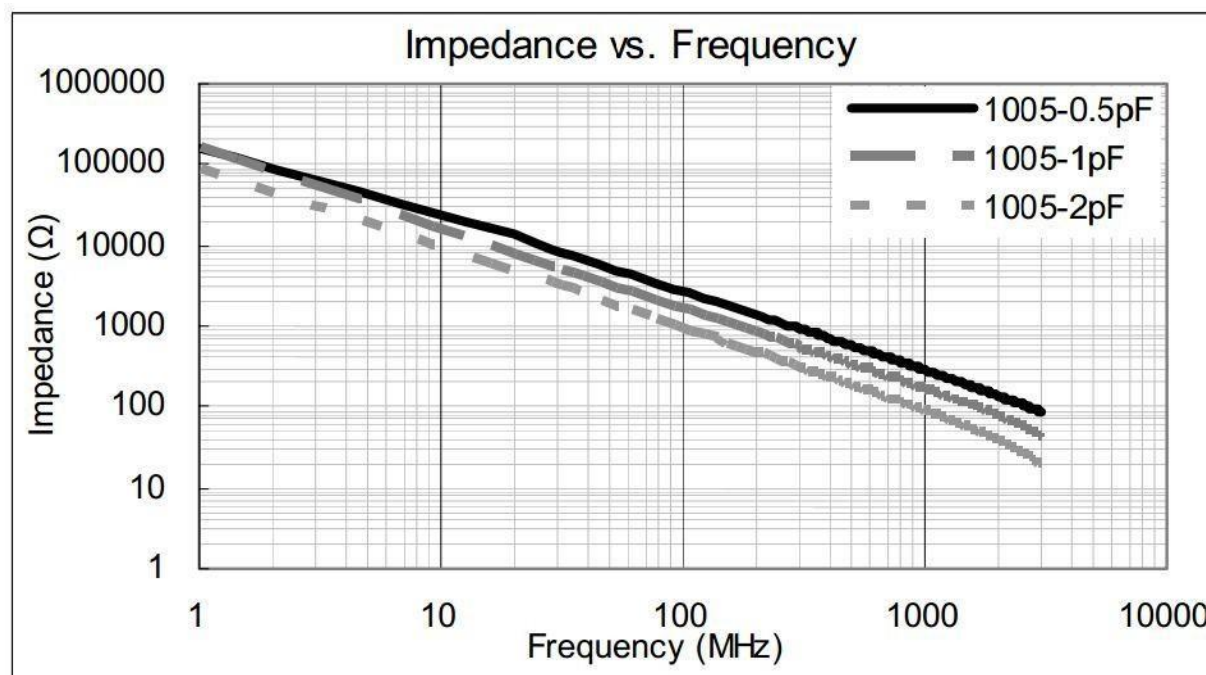
Technical Data	Symbol	Value	Unit
Maximum allowable continuous DC voltage	V _{DC}	5.0	V
Varistor voltage Measured*2	V _B	130	V
Varistor voltage tolerance		±20	%
Typical capacitance value measured*3	C	1.0	pF
Typical capacitance value tolerance		±0.3	PF
Maximum clamping voltage measured*4	V _C	250	V

Reference Data

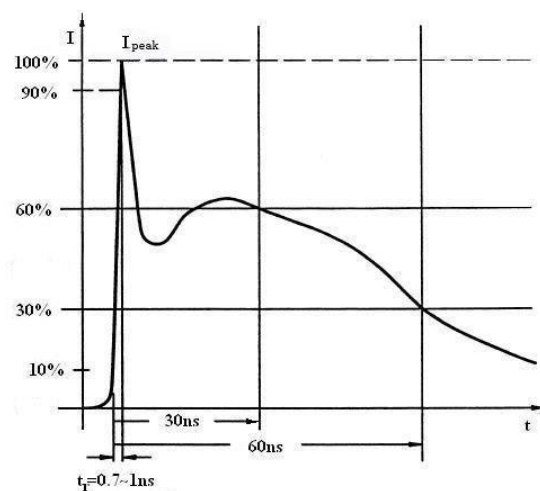
Response time	T _{rise}	<1	ns
Leakage current at V _B ×80%(At initial state)	I _{LVB}	<20	μ A
Leakage current at V _B ×80%(After reliability Test)	I _{LVBA}	<100	μ A
Operating ambient temperature		— 55~+125	℃
Storage temperature		— 40~+125	℃
Reflow temperature profile(Recommend)		260	℃

V-I characteristic





Esd Wave Form



IEC61000-4-2 Standards

SEVERITY LEVEL	AIRDIRCHARGE	DIRECT ISCHARGE
1	2 kV	2 kV
2	4 kV	4 kV
3	8 kV	6 kV
4	15 kV	8 kV

IEC61000-4-2 Compliant ESD Current Pulse Waveform

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